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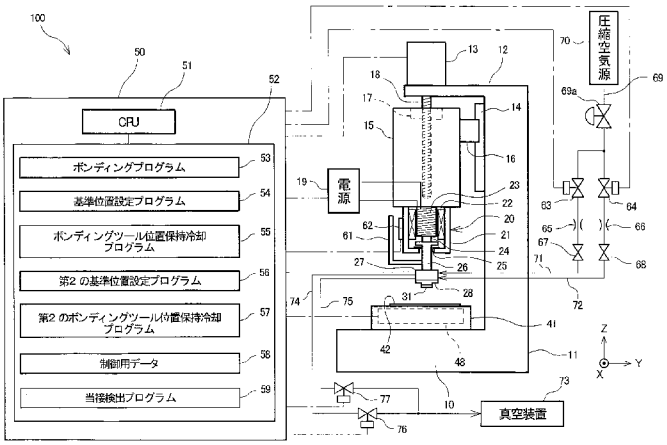
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— 国際調査報告（条約第 21 条(3)）

(54) **Title**: ELECTRONIC COMPONENT MOUNTING APPARATUS AND ELECTRONIC COMPONENT MOUNTING METHOD

(54) 発明の名称 : 電子部品実装装置及び電子部品実装方法

[図1]



53 BONDING PROGRAM
54 PROGRAM FOR SETTING REFERENCE POSITION
55 PROGRAM FOR MAINTAINING/COOLING BONDING TOOL POSITION
56 PROGRAM FOR SETTING SECOND REFERENCE POSITION
57 PROGRAM FOR MAINTAINING/COOLING SECOND BONDING TOOL POSITION
58 DATA FOR CONTROL
59 PROGRAM FOR DETECTING ABUTTING
19 POWER SUPPLY
70 COMPRESSED AIR SOURCE
73 VACUUM APPARATUS

(57) **Abstract**: Disclosed is an electronic component mounting apparatus, which bonds together the electrode of an electronic component (31) and the electrode of a substrate by having therebetween a bonding metal that melts with heat, and which mounts the electronic component (31) on the substrate. The electronic component mounting apparatus is provided with: a heater base (27a), which is driven in the direction in which the heater base is brought close to or far from the substrate, and which has a built-in ceramic heater (27h); and a bonding tool (28), which has the upper surface (28a) adhered to and fixed on the lower surface of the heater base (27a), and a base (28c) formed on the lower surface (28b) so as to suck and hold the electronic component (31), and which is heated by means of the ceramic heater (27h) in the heater base (27a), and bonds the electronic component (31) sucked to the base (28c) to the substrate by thermocompression bonding. The bonding tool (28) has a cooling flow channel that connects between the upper surface (28a) and the side surface (28d) of the base (28c). Consequently, a cooling time required at the time of mounting the electronic component is shortened.

(57) 要約:

[続葉有]

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